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### Packages with metal line crack prevention design

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#### Abstract

A package includes a corner, a device die, a plurality of redistribution lines underlying the device die, and a plurality of metal pads electrically coupled to the plurality of redistribution lines. The plurality of metal pads includes a corner metal pad closest to the corner, wherein the corner metal pad is a center-facing pad having a bird-beak direction substantially pointing to a center of the package. The plurality of metal pads further includes a metal pad farther away from the corner than the corner metal pad, wherein the metal pad is a non-center-facing pad having a bird-beak direction pointing away from the center of the package.

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## Background/Summary

**PRIORITY CLAIM AND CROSS-REFERENCE** (1) This application is a continuation of U.S. patent application Ser. No. 17/361,791, entitled “Packages with Metal Line Crack Prevention Design,” filed on Jun. 29, 2021, which is a continuation of U.S. patent application Ser. No. 15/914,102, entitled “Packages with Metal Line Crack Prevention Design,” filed on Mar. 7, 2018, now U.S. Pat. No. 11,056,464, issued Jul. 6, 2021, which is a continuation of U.S. patent application Ser. No. 14/244,111, entitled “Packages with Metal Line Crack Prevention Design,” filed on Apr. 3, 2014, now U.S. Pat. No. 9,929,126 issued Mar. 27, 2018, which applications are incorporated herein by reference.

### BACKGROUND

(1) In the packaging of integrated circuits, there are various types of packaging methods and structures. For example, in a conventional Package-on-Package (POP) process, a top package is bonded to a bottom package. The top package and the bottom package may also have device dies packaged therein. By adopting the PoP process, the integration level of the packages is increased. (2) In an existing PoP process, the bottom package is formed first, which includes a device die bonded to a package substrate. A molding compound is molded on the package substrate, wherein the device die is molded in the molding compound. The package substrate further includes solder balls formed thereon, wherein the solder balls and the device die are on a same side of the package substrate. The solder balls are used for connecting the top package to the bottom package.

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## Description

### BRIEF DESCRIPTION OF THE DRAWINGS

(1) Aspects of the present disclosure are best understood from the following detailed description when read with the accompanying figures. It is noted that, in accordance with the standard practice in the industry, various features are not drawn to scale. In fact, the dimensions of the various features may be arbitrarily increased or reduced for clarity of discussion. (2) FIG. 1 illustrates a cross-sectional view of a package in accordance with some embodiments; (3) FIG. 2 illustrates a bottom view of a Redistribution layer (RDL) pad in accordance with some embodiments, wherein the RDL pad includes a main pad region and a bird-beak region connected to the main pad region; (4) FIGS. 3 and 4 illustrate bottom views of packages and RDL pads in accordance with some embodiments, wherein center-facing pads and randomly-pointed RDL pads are distributed depending on their distances to neutral-stress points of the packages; (5) FIG. 5 illustrates a bottom view of some randomly-pointed RDL pads in accordance with some embodiments;

(6) FIG. 6 illustrates a bottom view of a package and RDL pads in accordance with some embodiments, wherein center-facing pads are formed in rectangular corner regions of the package; (7) FIGS. 7 and 8 illustrate the bottom views of packages and RDL pads in accordance with some embodiments, wherein the corner RDL pads adjacent to the corners of device dies have bird-beak directions pointing to the centers of the respective device dies; and (8) FIGS. 9A through 9J illustrate bottom views of some exemplary corner RDL pads with respective to the corners of the device dies.

#### DETAILED DESCRIPTION

(9) The following disclosure provides many different embodiments, or examples, for implementing different features of the invention. Specific examples of components and arrangements are described below to simplify the present disclosure. These are, of course, merely examples and are not intended to be limiting. For example, the formation of a first feature over or on a second feature in the description that follows may include embodiments in which the first and second features are formed in direct contact, and may also include embodiments in which additional features may be formed between the first and second features, such that the first and second features may not be in direct contact. In addition, the present disclosure may repeat reference numerals and/or letters in the various examples. This repetition is for the purpose of simplicity and clarity and does not in itself dictate a relationship between the various embodiments and/or configurations discussed.

(10) Further, spatially relative terms, such as “underlying,” “below,” “lower,” “overlying,” “upper” and the like, may be used herein for ease of description to describe one element or feature's relationship to another element(s) or feature(s) as illustrated in the figures. The spatially relative terms are intended to encompass different orientations of the device in use or operation in addition to the orientation depicted in the figures. The apparatus may be otherwise oriented (rotated 90 degrees or at other orientations) and the spatially relative descriptors used herein may likewise be interpreted accordingly.

(11) A package and the method of forming the package are provided in accordance with various exemplary embodiments. The variations of the embodiments are discussed. Throughout the various views and illustrative embodiments, like reference numbers are used to designate like elements.

(12) FIG. 1 illustrates a cross-sectional view of package 20 in accordance with some embodiments. Package 20 includes package 100 and package 200 over and bonded to package 100. In some embodiments, package 100 includes device dies 102, with the front sides of device dies 102 facing down and bonded to Redistribution Layers (RDLs) 132/134/136. Throughout the description, the term “RDL” also refers to the redistribution lines in the redistribution layers. In alternative embodiments, package 100 includes a single device die or more than two device dies. Device die 102 may include semiconductor substrate 108, and integrated circuit devices 104 (such as active devices, which include transistors, for example) at the front surface (the surface facing down) of semiconductor substrate 108. Device die 102 may include a logic die such as a Central Processing Unit (CPU) die, a Graphic Processing Unit (GPU) die, a mobile application die, or the like.

(13) Device dies 102 are molded in molding material 120, which surrounds each of device dies 102. Molding material 120 may be a molding compound, a molding underfill, a resin, or the like. The bottom surface 120A of molding material 120 may be level with the bottom ends of device dies 102. The top surface 120B of molding material 120 may be level with or higher than back surface 108A of semiconductor substrate 108. In some embodiments, back surface 108A of semiconductor substrate 108 is overlapped by die-attach film 110, which is a dielectric film adhering device die 102 to the overlying dielectric layer 118. Device die 102 further includes metal pillars/pads 106 (which may include copper pillars, for example) in contact with, and bonded to, RDLs 132.

(14) Package 100 may include bottom-side RDLs 132/134/136 underlying device dies 102, and top-side RDLs 116 overlying device dies 102. Bottom-side RDLs 132/134/136 are formed in dielectric layers 114, and top-side RDLs 116 are formed in dielectric layers 118. RDLs

**132/134/136** and **116** may be formed of copper, aluminum, nickel, titanium, alloys thereof, or multi-layers thereof. In some embodiments, dielectric layers **114** and **118** are formed of organic materials such as polymers, which may further include polybenzoxazole (PBO), benzocyclobutene (BCB), polyimide, or the like. In alternative embodiments, dielectric layers **114** and **118** are formed of inorganic material such as silicon oxide, silicon nitride, silicon oxynitride, or the like.

(15) Through-Vias **122** are formed to penetrate through molding material **120**. In some embodiments, through-vias **122** have top surfaces level with the top surface **120B** of molding material **120**, and bottom surfaces level with the bottom surface **120A** of molding material **120**. Through-Vias **122** electrically couple bottom-side RDLs **132/134/136** to top-side RDLs **116**. Through-Vias **122** may also be in physical contact with bottom-side RDLs **132** and top-side RDLs **116**.

(16) Electrical connectors **124**, which are formed of a non-solder metallic material(s), are formed at the bottom surface of package **100**. In some embodiments, electrical connectors **124** include Under-Bump Metallurgies (UBMs), which are also metal pads. In alternative embodiments, electrical connectors **124** are metal pads, metal pillars, or the like. Metal pads **124** may comprise copper, aluminum, titanium, nickel, palladium, gold, or multi-layers thereof. In some embodiments, the bottom surfaces of metal pads **124** extend below the bottom surface of the bottom dielectric layer **114**, as shown in FIG. 1. Solder regions **126** may be attached to the bottom surfaces of metal pads **124**.

(17) In some embodiments, RDLs **132/134/136** include portions (including **132** and **134**) in more than one metal layers and vias **136** interconnecting the RDLs in different metal layers. For example, FIG. 1 illustrates RDLs **132**, which are closest to through-vias **122**. The bottom surfaces of through-vias **122** are in contact with some of RDLs **132**. Furthermore, metal pillars **106** of device die **102** are also in contact with some of RDLs **132**. Electrical connectors **124** are electrically coupled to, and may be in physical contact with, RDLs **134**. Hence, RDLs **134** may be in the metal layer that is closest to electrical connectors **124**. Vias **136** are disposed between, and electrically interconnect, RDLs **132** and RDLs **134**.

(18) FIG. 2 illustrates a bottom view of one of RDLs **134**. The illustrated RDL **134** includes main pad region **138**, metal trace **142**, and bird-beak region **140** connecting main pad region **138** to metal trace **142**. In accordance with some embodiments, main pad region **138** has a round bottom-view shape. In alternative embodiments, main pad region **138** may have other applicable shapes including, and not limited to, rectangles, hexagons, octagons, and the like. bird-beak region **140** is the region that has widths gradually and/or continuously transition from the width of main pad region **138** to the width of metal trace **142**. Metal trace **142** has one end connected to one of vias **136**, which leads to RDLs **132** (FIG. 1).

(19) Arrow **144** is drawn to show the direction pointing from the center of main pad region **138** to the center (FIGS. 3, 4, and 6-8) of bird-beak region **140**. Direction **144** may also point from the center of main pad region **138** to the connecting point between bird-beak region **140** and metal trace **142**. Main pad region **138** and bird-beak region **140** in combination form an RDL pad **146** for supporting and connecting to electrical connector **124** (FIG. 1). Throughout the description, direction **144** is referred to the bird-beak direction of the respective RDL pad **146** and the bird-beak direction of the respective RDL **134**.

(20) FIG. 3 illustrates an exemplary bottom view of bottom package **100**, wherein RDL pads **146** (and some of RDL traces) are illustrated. RDLs **134** include center-facing pads (sometimes referred to as center-facing metal pads hereinafter) **146A** and randomly-pointed pads **146B**. In FIGS. 3 through 9J, circles are used to schematically represent randomly-pointed RDL pads **146B**. Center-facing pads **146A**, however, are illustrated with more details to indicate their bird-beak directions. For example, the main pad region, the bird-beak region, and the respective bird-beak direction of center-facing pads **146A** are schematically illustrated.

(21) FIG. 5 illustrates the bottom views (or top views) of exemplary randomly-pointed RDL pads

**146B** with more details, wherein the randomly-pointed RDL pads **146B** are shown in FIGS. **3**, **4**, and **6** through **9J**. FIG. **5** schematically illustrate an inner region **153** (also refer to FIGS. **3** and **4**) of package **wo** and the randomly-pointed RDL pads **146B** therein. As shown in FIG. **5**, randomly-pointed RDL pads **146B** may have the similar shapes as center-facing pads **146A**. For example, randomly-pointed RDL pads **146B** may also include main pad regions, and bird-beak regions connected to the respective main pad regions. There are also metal traces connected to the bird-beak regions, with the metal traces further connected to vias **136**.

(22) As shown in FIG. **5**, the bird-beak directions of randomly-pointed RDL pads **146B** are randomly disposed, and can be in any directions. Therefore, each of the bird-beak directions of randomly-pointed pads **146B** may be in any direction, including center-facing and non-center-facing. For example, the bird-beak directions of randomly-pointed RDL pads **146B** do not necessarily point to the center of package **100** (FIGS. **1** and **3**), and do not necessarily point to the center of any device die in package **100**. Furthermore, neighboring randomly-pointed RDL pads **146B** may have different bird-beak directions.

(23) Referring back to FIG. **3**, bottom package **wo** includes four corners **148**. The corner RDL pads **146**, which are closer to the respective corners **148** than all other metal pads, are center-facing pads **146A**, which have their bird-beak directions pointing to (or substantially pointing to) center **150** of package **100**. Other RDL pads **146** that are farther away from the respective corners **148** than the corner RDL pads **146A** are randomly-pointed RDL pads **146B**. In some embodiments, there may be more than one center-facing pad **146A** at each corner **148**. For example, FIG. **4** illustrates three center-facing pads **146A** at each corner **148**.

(24) FIG. **4** also illustrates the bottom view of bottom package **wo** and RDL pads **146** in accordance with alternative embodiments. In the bottom view, bottom package **wo** has neutral-stress point **150**, which is the point that is substantially free from stresses from all lateral directions that are parallel to the bottom surface of package **100**. At neutral-stress point **iso**, the lateral stresses from opposite directions are cancelled out. In some embodiments, neutral-stress point **150** is at or close to the center (also marked as **iso**) of bottom package **100** (in the bottom view). The distance of each of RDL pads **146** to neutral-stress point **150** is referred to as a Distance to Neutral Point (DNP), wherein the distance to the RDL pads **146** may be measured from a point of the RDL pad **146** that is farthest to neutral-stress point **iso**. For example, DNPs **DNP1** and **DNP2** are illustrated as examples in FIG. **4**.

(25) Referring to FIGS. **3** and **4**, circle **152** is drawn with the neutral-stress point **150** as the center, wherein circle **152** has radius  $r$ . In accordance with the embodiments of the present disclosure, all RDL pads **146** with the DNPs equal to or smaller than radius  $r$  may be designed as randomly-pointed RDL pads **146B**, and all RDL pads **146** with DNPs greater than radius  $r$  are designed to be center-facing pads **146A**. Some or all RDL pads **146** with the DNPs equal to or smaller than radius  $r$  may also be designed as center-facing pads **146A**. As illustrated in FIG. **3**, if radius  $r$  is large, then the center-facing pads **146A** may only include a single corner RDL pad **146** at each corner **148**. In FIG. **4**, radius  $r$  is reduced, and more corner RDL pads **146** are designed as center-facing pads **146A**, while the RDL pads **146** with the DNPs equal to or smaller than radius  $r$  are randomly pointed, and do not necessarily point to the center **150**. The optimum radius  $r$  of circle **152** may be determined by simulation or experiment (by forming physical chips), so that the reliability of the RDLs **146** inside the circle **152** meets design specification.

(26) In FIG. **4**, the center-facing pads **146A** at the same corner may have their bird-beak directions parallel to each other. This means that the bird-beak directions of some of center-facing pads **146A** (marked as **146A'**) are actually slightly offset from the center **150**. In alternative embodiments, all center-facing pads **146A** at the same corner **148** may have bird-beak directions pointing right at center **150** of package **100**, which means that their bird-beak directions are substantially, but not exactly, parallel to each other.

(27) FIG. **6** illustrates the design of RDL pads **146** in accordance with yet alternative embodiments.

In these embodiments, four corner regions **154** of bottom package **wo** are defined, each extending from one of corners **148** inwardly. The four corner regions **154** may have rectangular shapes, and may have sizes the same as each other. The RDL pads **146** inside corner regions **154** are designed as center-facing pads **146A**. The RDLs outside corner regions **154** may be designed as randomly-pointed RDL pads **146B**, or may be designed as center-facing pads **146A**.

(28) In some embodiments as in FIG. **6**, circle **152** is also drawn according to simulation or experiment results. The radius of circle **152** may be small, and hence some of RDL pads **146** that are outside of corner regions **154** are also outside of circle **152**. Accordingly, as shown in FIG. **6**, some of RDL pads **146** (marked as **146''**) that are outside of the circle **152** are also center-facing pads **146A**, while the RDL pads **146** that are outside of corner regions **154**, but inside circle **152**, are randomly-pointed RDL pads **146B**.

(29) FIGS. **7** and **8** illustrate the bottom views of package **wo** in the embodiments in which the RDL pads **146** adjacent to the corners of device die(s) **102** (FIG. **1**) are also designed as center-facing pads **146A**. These embodiments may be combined with the embodiments in FIGS. **3**, **4**, and **6**, so that the center-facing pads **146A** as shown in FIGS. **3**, **4**, and **6** may also be designed as center-facing pads **146A**, in addition to the RDL pads **146A** adjacent to the corners of device die(s) **102**.

(30) Referring to FIG. **7**, device die **102** is illustrated. Device die **102** includes corners **102A**. At each of corners **102A**, device die **102** overlaps (Refer to FIG. **1**) at least a portion of one RDL pad **146A**. The neighboring RDL pads **146** adjacent to corners **102A** are designed as center-facing pads **146A**, wherein the neighboring RDL pads **146** are referred to as corner RDL pads **146** hereinafter. The corner RDL pads **146** of device die **102**, instead of having bird-beak directions pointing to the center **150** of package **100**, have bird-beak directions pointing to center **156** of device die **102**. The corner RDL pads **146**, which are center-facing pads, may be fully surrounded by randomly-pointed RDL pads. Similarly, the corner RDL pads **146A** close to the same corner of device die **102** may have their bird-beak directions parallel to each other, although the bird-beak directions may also point exactly to center **156**, hence are substantially, but not exactly, parallel to each other. Hence, throughout the description, when an RDL pad **146** is referred to as “center-facing,” the bird-beak direction of the RDL pad **146** may point to the center of the respective package, or the center of a device die, depending on where the RDL pad is located.

(31) FIG. **8** illustrates the bottom view of package **boo** in accordance with alternative embodiments. These embodiments are similar to the embodiments in FIG. **7**, except that there are two device dies **102** disposed in bottom package **100**. The corner RDL pads **146** that are adjacent to the corners of each of device dies **102** are designed as center-facing pads **146A**. For each of the device dies **102**, the respective corner RDL pads **146A** have their bird-beak directions pointing to the center **156** of the respective device die **102**.

(32) FIGS. **9A** through **9J** are the exemplary embodiments for defining what are the corner RDL pads of the device dies. Throughout FIG. **9A** through **9J**, nine RDL pads **146** are illustrated, and are marked with sequence numbers range from 0 to 8, with the one with the sequence number 0 (referred to as the 0.sup.th RDL pad **146** hereinafter) being the central one of the nine RDL pads **146**. Furthermore, throughout FIGS. **9A** through **9J**, dx represents the X-direction distance from the center of the 0.sup.th RDL pad **146** to the vertical edge **102B1** of device die **102**, and dy represents the Y-direction distance from the center of the 0.sup.th RDL pad **146** to the horizontal edge **102B2**. Pitch **P1** represents the pitches of neighboring RDL pads **146**, which are, for example, the distances between the centers of the main pad region **138** (FIG. **2**) of neighboring RDL pads **146**.

Furthermore, in subsequently recited equations, the value “a” represents the diameter of RDL pads **146**, as shown in FIG. **2**. In each of the FIGS. **9A** through **9J**, the RDL pads **146** in rectangular region **158** (referred to as corner region hereinafter) are defined as corner RDLs, and are designed as center-facing pads. Hence, the center-facing pads include the 0.sup.th, the 1st, the 2.sup.nd, and the 4.sup.th RDL pads **146**. The 1st, the 2.sup.nd, and the 4.sup.th RDL pads **146** are the pads that

are not overlapped by device die **102**, and are closest to corner **102A**. The remaining RDL pads **146** may be randomly-pointed RDL pads, which may include the 3.sup.rd, the 5.sup.th, the 6.sup.th, the 7.sup.th, and the 8.sup.th RDL pads **146**.

(33) FIGS. **9A**, **9B**, and **9C** illustrate the embodiments wherein the 0.sup.th RDL pad **146** is fully overlapped by device die **102**, and rest of the corner RDL pads **146** are not overlapped by device die **102**. For example, if one of RDL pads **146** satisfies both of the following two relationships:

$$a/2 \leq dx \leq (P1 - a/2) \quad [\text{Eq. 1}]$$

$$a/2 \leq dy \leq (P1 - a/2) \quad [\text{Eq. 2}]$$

the respective RDL pad **146** is the 0.sup.th RDL, and the respective corner region **158** and the RDL pads in the corner region **158** can be identified, as illustrated. In FIG. **9A**, the 0.sup.th RDL pad **146** does not have any point overlapped by edges **102B1** and **102B2**. In FIG. **9B**, the 0.sup.th RDL pad **146** has a point aligned to edge **102B1**, and the 0.sup.th RDL pad **146** and device die **102** have no overlap. In FIG. **9C**, dx is equal to (P1-a/2), which means that the 4.sup.th RDL pad **146** has a point aligned to edge **102B1**, and the 4.sup.th RDL pad **146** and device die **102** have no overlap.

(34) FIGS. **9D**, **9E**, and **9F** illustrate the embodiments wherein the 0.sup.th RDL pad **146** are partially overlapped by the respective device die **102**. Furthermore, the corner **102A** of device die **102** also overlaps the 0.sup.th RDL pad **146**. For example, if one of RDL pads **146** satisfies both of the following two relationships:

$$dx < a/2 \quad [\text{Eq. 3}]$$

$$dy < a/2 \quad [\text{Eq. 4}]$$

the respective RDL pads **146** is the 0.sup.th RDL, and the respective corner region **158** and the RDL pads in the corner region **158** can be identified. In FIGS. **9D** and **9E**, the centers of the 0.sup.th RDL pad **146** are not overlapped by the respective device dies **102**. In FIG. **9F**, the center of the 0.sup.th RDL pad **146** is overlapped by device die **102**.

(35) FIGS. **9G** through **9J** illustrate the embodiments wherein the 0.sup.th RDL pad **146** is partially overlapped by device die **102**. Furthermore, edge **102B2** overlaps the 0.sup.th RDL pad **146**, while the corner **102A** of device die **102** does not overlap the 0.sup.th RDL pad **146**. For example, if one of RDL pads **146** satisfies both of the following two relationships:

$$a/2 \leq dx \leq (P1 - a/2) \quad [\text{Eq. 5}]$$

$$dy < a/2 \quad [\text{Eq. 6}]$$

the respective RDL pads **146** is the 0.sup.th RDL pad, and the respective corner region **158** and the RDL pads in the corner region **158** can be identified. In FIGS. **9G**, **9H**, and **9I**, the centers of the respective 0.sup.th RDL pads **146** are overlapped by the respective device dies **102**. Furthermore, FIGS. **9G**, **9H**, and **9I** illustrate the embodiments in which dx is equal to, smaller than, and greater than, (P1)/2. In FIG. **9J**, the center of the 0.sup.th pad RDL pad **146** is not overlapped by device die **102**.

(36) The embodiments of the present disclosure have several advantageous features. The RDL pads that are close to the corners of package **wo** and device die **102** suffer from high stresses, and hence the RDL traces of these RDL pads are more likely to be broken by the stresses. Experiment results and simulation results indicate that the center-facing pads are more reliable, and the stresses suffered by the traces connected to the center-facing pads are lower than the stresses suffered by the randomly-pointed RDL pads. Accordingly, by designing the RDL pads that suffer from higher stresses as center-facing, the reliability of the respective package is improved. On the other hand, the RDL pads suffer from low stresses may have their bird-beak directions pointing randomly to improve the flexibility in RDL routing.

(37) In accordance with some embodiments of the present disclosure, a package includes a corner, a device die, a plurality of redistribution lines underlying the device die, and a plurality of metal pads electrically coupled to the plurality of redistribution lines. The plurality of metal pads includes a corner metal pad, wherein the corner metal pad is a center-facing pad having a bird-beak direction substantially pointing to a center of the package. The plurality of metal pads further includes a



metal pad farther away from the corner than the corner metal pad, wherein the metal pad is a non-center-facing pad having a bird-beak direction pointing away from the center of the package.

(38) In accordance with alternative embodiments of the present disclosure, a package includes at least one first dielectric layer, a first plurality of redistribution lines in the at least one first dielectric layer, a device die over and electrically coupled to the first plurality of redistribution lines, a molding material molding the device die therein, a through-via penetrating through the molding material, and at least one second dielectric layer over the device die. A second plurality of redistribution lines is in the at least one second dielectric layer. The second plurality of redistribution lines is electrically coupled to the first plurality of redistribution lines through the through-via. A plurality of metal pads is underlying the device die and electrically coupled to the second plurality of redistribution lines. The plurality of metal pads includes a first center-facing metal pad and a non-center-facing metal pad.

(39) In accordance with yet alternative embodiments of the present disclosure, a package includes a plurality of dielectric layers, a plurality of redistribution lines in the plurality of dielectric layers, a device die over and electrically coupled to the plurality of redistribution lines, and a plurality of metal pads underlying and electrically coupled to the plurality of redistribution lines. The plurality of metal pads includes a corner metal pad, wherein the corner metal pad has a first bird-beak direction pointing to a first center of a package that includes the plurality of metal pads and the device die. The plurality of metal pads further includes an inner metal pad adjacent to a corner of the device die, wherein the inner electrical has a second bird-beak direction pointing to a second center of the device die. The plurality of metal pads also includes a plurality of non-center-facing metal pads surrounding the inner metal pad.

(40) The foregoing outlines features of several embodiments so that those skilled in the art may better understand the aspects of the present disclosure. Those skilled in the art should appreciate that they may readily use the present disclosure as a basis for designing or modifying other processes and structures for carrying out the same purposes and/or achieving the same advantages of the embodiments introduced herein. Those skilled in the art should also realize that such equivalent constructions do not depart from the spirit and scope of the present disclosure, and that they may make various changes, substitutions, and alterations herein without departing from the spirit and scope of the present disclosure.

## Claims

1. A structure comprising: a first package comprising: a device die comprising a first center in a top view of the first package; an encapsulant encapsulating the device die therein; a center metal pad; and a plurality of metal pads surrounding the center metal pad and forming a first array along with the center metal pad, wherein the plurality of metal pads comprise: a first plurality of metal pads vertically offset from the device die; and a second plurality of metal pads overlapped by the device die, wherein the first array comprises four metal pads that are closer to a corner of the device die than rest of five metal pads of the first array, and wherein the four metal pads form a second array, and the four metal pads comprise bird beaks pointing to the first center of the device die; and a second package bonding to the first package.
2. The structure of claim 1, wherein some of the rest of five metal pads comprise additional bird beaks pointing to the first center of the device die.
3. The structure of claim 1, wherein some of the rest of five metal pads comprise additional bird beaks pointing away from the first center of the device die.
4. The structure of claim 1, wherein the first package has a second center in the top view, and the second center is offset from the first center of the device die.
5. The structure of claim 1, wherein the center metal pad is fully overlapped by the device die.
6. The structure of claim 1, wherein the center metal pad is partially overlapped by the device die.

7. The structure of claim 1, wherein in the top view, the center metal pad comprises a pad center overlapped by the device die, and wherein rest of three metal pads in the four metal pads are overlapped by the device die.
  8. The structure of claim 1, wherein in the top view, the center metal pad comprises a pad center overlapped by the device die, and wherein rest of three metal pads in the four metal pads are vertically offset from the device die.
  9. The structure of claim 1 further comprising: a plurality of under-bump metallurgies physically contacting the plurality of metal pads; and a plurality of solder regions physically contacting the plurality of under-bump metallurgies.
  10. The structure of claim 9, wherein the plurality of solder regions are in physical contact with the second package.
  11. The structure of claim 9 further comprising: a plurality of dielectric layers underlying the device die; and a plurality of layers of redistribution lines in the plurality of dielectric layers, wherein the plurality of metal pads are over and in physical contact with a bottommost dielectric layer of the plurality of dielectric layers.
  12. A structure comprising: a device die comprising a first center; an encapsulant encapsulating the device die therein; and a plurality of metal pads forming an array comprising three rows and three columns, the array comprising: a first metal pad fully overlapped by the device die; a second metal pad fully vertically offset from the device die; and a center metal pad in middle of the first metal pad and the second metal pad, wherein the center metal pad is at least partially overlapped by the device die, and wherein the center metal pad comprises a bird beak pointing to the first center of the device die.
  13. The structure of claim 12 comprising a package, with the device die and the plurality of metal pads being parts of the package, wherein in a top view of the structure, the package comprises a second center offset from the first center.
  14. The structure of claim 13, wherein in the top view of the structure, the bird beak of the center metal pad points away from the second center of the package.
  15. The structure of claim 12, wherein the first metal pad comprises a first additional bird beak pointing toward the first center, and the second metal pad comprises a second additional bird beak pointing away from the first center.
  16. The structure of claim 12, wherein the center metal pad is partially overlapped by the device die.
  17. The structure of claim 12, wherein the center metal pad is fully overlapped by the device die.
  18. A structure comprising: a device die; and a plurality of metal pads below the device die, wherein the plurality of metal pads comprise: an array of metal pads comprising a plurality of rows and a plurality of columns of metal pads, wherein the array of metal pads comprises: a center metal pad at a center of the array, wherein the center metal pad is closer to a corner of the device die than all other ones of the plurality of metal pads; a first metal pad overlapped by the device die; and a second metal pad vertically offset from the device die, wherein the center metal pad, the first metal pad and the second metal pad are aligned to a same straight line, with the first metal pad and the second metal pad being on opposite sides of the center metal pad, and the center metal pad comprises a first bird beak pointing to a die center of the device die, and wherein one of the first metal pad and the second metal pad that is closer to the corner of the device die than another one of the first metal pad and the second metal pad comprises a second bird beak pointing to the die center of the device die.
  19. The structure of claim 18, wherein the another one of the first metal pad and the second metal pad comprises an additional bird beak pointing away from the die center.
  20. The structure of claim 18, wherein the first bird beak of the first metal pad points to the die center of the device die.
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